

IN THE SPECIFICATION:

Please amend the first paragraph on page 10, lines 1-12 as follows:

---

-- Referring again to Figs. 1 and 2, machine vision system 20 is shown including a camera 60 in attachment to a support 65. Support 65 is shown with a ~~second~~ first attachment mechanism 50. Camera 60 is configured to locate the position of semiconductor device 25 in relation to the position of probe assembly 10. More particularly, camera 60 locates the position of contact pads 30 in relation to electrical probes 35. Using this location information, machine vision system 20 guides motion stage 55 so as to position semiconductor support 15 in the X-direction and/or the Y-direction. This positioning is continued until contact pads 30 are positioned in alignment with electrical probes 35. --

---